

客户图

NOTES:

1. MATERIAL:

- HOUSING: LCP BLACK,UL94V-0.
- CONTACT: BeCu,GOLD (SEE P/N) PLATED IN CONTACT AREA, MATTE TIN PLATED IN SOLDER AREA, 50u" MIN. NICKEL UNDERPLATED OVERALL.

2. ELECTRICAL:

- CURRENT RATING: 1.5 A PER PIN.
- OPERATION TEMPERATURE:-55°C TO +125°C.

3.ORDER INFORMATION:

66F3-F-XX-XX-G4-XXX-R-01

SEE:TABLE 1
No.OF POS

-10
-15
...

SEE:TABLE 2
No OF ROWS

-04
-05
...

端子电镀:

G0=Gold Flash
G1=1u" Gold
G2=3u" Gold
G3=5u" Gold
G4=10u" Gold
G6=30u" Gold

塑胶高度 "H":

050=5.05mm
060=6.05mm
065=6.55mm
075=7.54mm

包装方式:

R=载带包装

TABLE 1

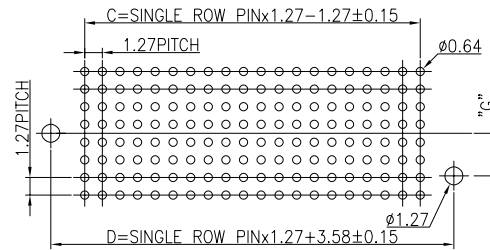
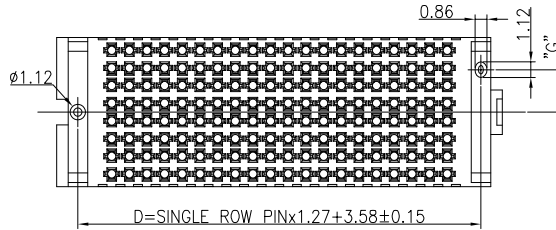
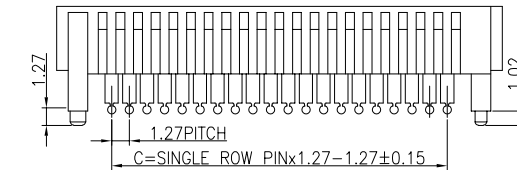
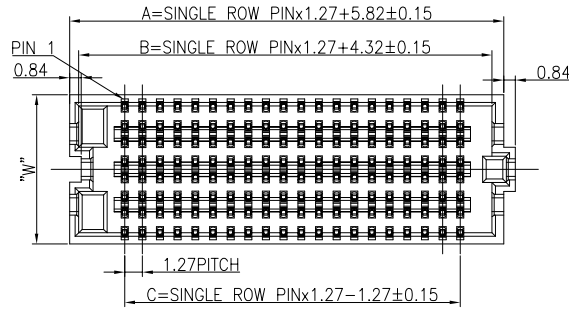
No.OF POS	"A"	"B"	"C"	"D"
-10	18.52	17.02	11.43	16.28
-15	24.87	23.37	11.78	22.63
-20	31.22	29.72	24.13	28.98
-30	43.92	42.42	36.83	41.68
-40	56.62	55.12	49.53	54.38
-50	69.32	67.82	62.23	67.08

TABLE 2

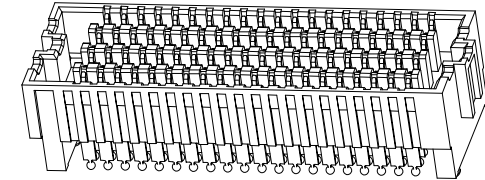
No OF ROWS	"W"	"G"
-04	5.66	2.01
-05,-06	8.20	3.05
-08	10.74	3.05
-10	13.28	3.05

TABLE 3

"H"
5.05
6.05
6.55
7.54

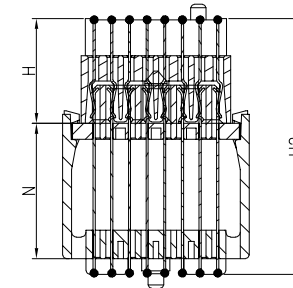
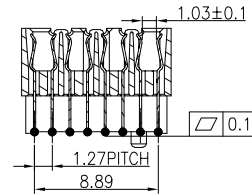
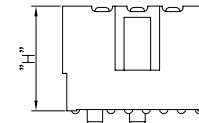


RECOMMENDED PCB LAYOUT(TOP SIDE)
PCB BOARD TOLERANCE±0.05



MATING HEIGHT

MATING HEIGHT	"N"	H1	H2
7.00mm	1.88	5.05	7.00
8.00mm	2.89	5.05	8.00
8.50mm	3.40	5.05	8.50
9.00mm	4.00	5.05	9.00
11.50mm	6.40	5.05	11.50
12.00mm	6.88	5.05	12.00
14.00mm	8.89	5.05	14.00
16.00mm	10.90	5.05	16.00
18.00mm	12.90	5.05	18.00
8.00mm	1.88	6.05	8.00
9.00mm	2.89	6.05	9.00
9.50mm	3.40	6.05	9.50
10.00mm	4.00	6.05	10.00
12.50mm	6.40	6.05	12.50
13.00mm	6.88	6.05	13.00
15.00mm	8.89	6.05	15.00
17.00mm	10.90	6.05	17.00
19.00mm	12.90	6.05	19.00
8.50mm	1.88	6.55	8.50
9.50mm	2.89	6.55	9.50
10.00mm	3.40	6.55	10.00
10.50mm	4.00	6.55	10.50
13.00mm	6.40	6.55	13.00
13.50mm	6.88	6.55	13.50
15.50mm	8.89	6.55	15.50
17.50mm	10.90	6.55	17.50
19.50mm	12.90	6.55	19.50
9.50mm	1.88	7.54	9.50
10.50mm	2.89	7.54	10.50
11.00mm	3.40	7.54	11.00
11.50mm	4.00	7.54	11.50
14.00mm	6.40	7.54	14.00
14.50mm	6.88	7.54	14.50
16.50mm	8.89	7.54	16.50
18.50mm	10.90	7.54	18.50
20.50mm	12.90	7.54	20.50



MATING HEIGHT

					OPERATION	DRAW	Mr.Zeng	2025.05.13	SOLEPIN 东莞市硕品电子有限公司 PROFESSIONAL CONNECTOR DONGGUAN SOLEPIN ELECTRONICS CO., LTD.			
					X.X ±0.40	DESIGN	Jensen	2025.05.13				
					X.XX ±0.25	CHECK	Jack	2025.05.13				
					X.XXX ±0.15	APPROVE	Andy	2025.05.13				
AO			NEW		Angle ±3°				SHEET	1/1	TITLE:	66F3-F-XX-XX-G4-XXX-R-01
REV	DATE		MODIFICATION DESCRIPTION	CHANGE	DIM. TOL	UNIT	mm	SCALE	1:1	PROJ.	DRAW NO.	SP-1737

客户图

NOTES:

1. MATERIAL:

- HOUSING: LCP BLACK,UL94V-0.
- CONTACT: BeCu,GOLD (SEE P/N) PLATED IN CONTACT AREA, MATTE TIN PLATED IN SOLDER AREA, 50u" MIN. NICKEL UNDERPLATED OVERALL.

2. ELECTRICAL:

- CURRENT RATING: 1.5 A PER PIN(4 PINS POWERED).
- OPERATION TEMPERATURE:-55°C TO +125°C.

3.ORDER INFORMATION:

66F3-M-XX-XX-G4-XXX-R-01

SEE:TABLE 1
No.OF POS
-10
-15
...
SEE:TABLE 2
No OF ROWS
-04
-05
...
端子电镀:
G0=Gold Flash
G1=1u" Gold
G2=3u" Gold
G3=5u" Gold
G4=10u" Gold
G6=30u" Gold
塑胶高度 "H":
056=5.61mm
066=6.60mm
071=7.11mm
077=7.71mm
包装方式:
R=载带包装

TABLE 1

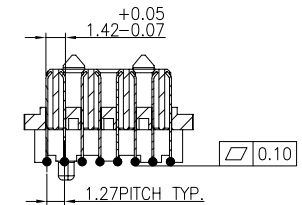
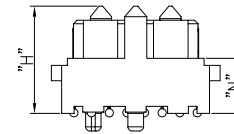
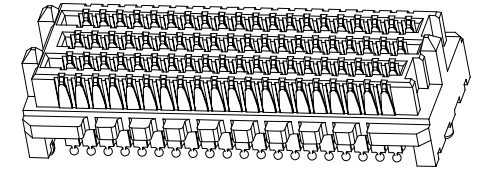
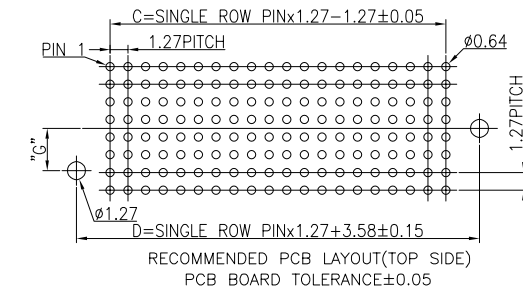
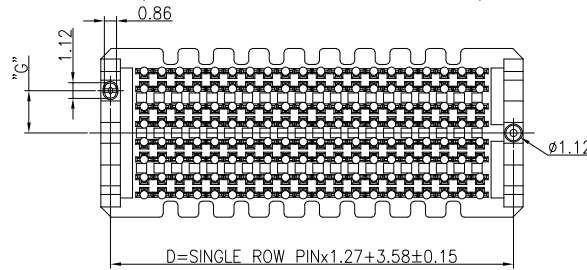
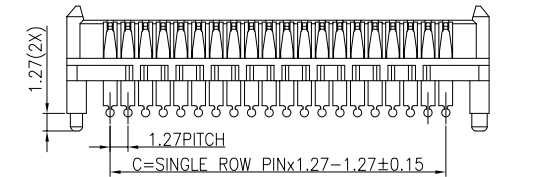
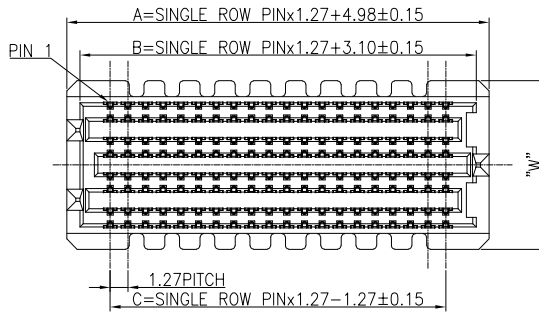
No.OF POS	"A"	"B"	"C"	"D"
-10	17.68	15.80	11.43	16.28
-15	24.03	22.15	11.78	22.63
-20	30.38	28.50	24.13	28.98
-30	43.08	41.20	36.83	41.68
-40	55.78	53.90	49.53	54.38
-50	68.48	66.60	62.23	67.08

TABLE 2

No OF ROWS	"W"	"G"
-04	7.06	2.01
-05,-06	9.60	3.05
-08	12.14	3.05
-10	14.68	3.05

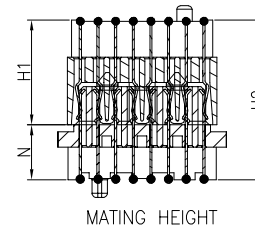
TABLE 3

"H"	"N"
5.61	1.88
6.60	2.89
7.11	3.40
7.71	4.00



MATING HEIGHT

MATING HEIGHT	"N"	H1	H2
7.00mm	1.88	5.05	7.00
8.00mm	2.89		8.00
8.50mm	3.40		8.50
9.00mm	4.00	6.05	9.00
8.00mm	1.88		8.00
9.00mm	2.89		9.00
9.50mm	3.40	6.55	9.50
10.00mm	4.00		10.00
8.50mm	1.88		8.50
9.50mm	2.89	7.54	9.50
10.00mm	3.40		10.00
10.50mm	4.00		10.50
9.50mm	1.88		9.50
10.50mm	2.89		10.50
11.00mm	3.40		11.00
11.50mm	4.00		11.50



OPERATION	DRAW	Mr.Zeng	2025.05.13
X.X ±0.40	DESIGN	Jensen	2025.05.13
X.XX ±0.25	CHECK	Jack	2025.05.13
X.XXX ±0.15	APPROVE	Andy	2025.05.13
Angle ±3°	UNIT	mm	SCALE 1:1
DIM. TOL			

SOLEPiN 东莞市硕品电子有限公司
PROFESSIONAL CONNECTOR DONGGUAN SOLEPIN ELECTRONICS CO., LTD.

REV	DATE	MODIFICATION DESCRIPTION	CHANGE	APPROVE
AO		NEW		

SIZE	A4	PART NO.	66F3-M-XX-XX-G4-XXX-R-01
SHEET	1/1	TITLE:	1.27mm PITCH BTB PLUG SMT
PROJ.	Φ	DRAW NO.	SP-1735

客户图

NOTES:

1. MATERIAL:

- HOUSING: LCP BLACK,UL94V-0.
- CONTACT: BeCu,GOLD (SEE P/N) PLATED IN CONTACT AREA, MATTE TIN PLATED IN SOLDER AREA, 50u" MIN. NICKEL UNDERPLATED OVERALL.

2. ELECTRICAL:

- CURRENT RATING: 1.5 A PER PIN(4 PINS POWERED).
- OPERATION TEMPERATURE:-55°C TO +125°C.

3.ORDER INFORMATION:

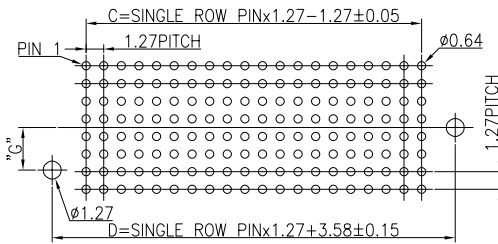
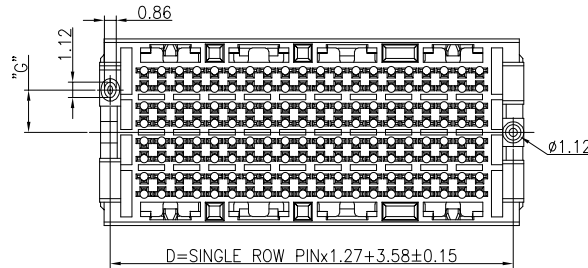
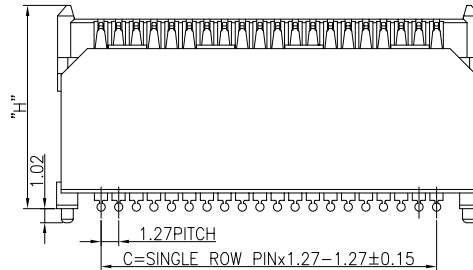
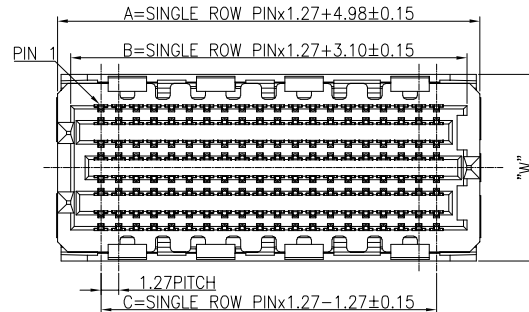
66F3-M-XX-XX-G4-XXX-R-02

SEE:TABLE 1	端子电镀:	塑胶高度 "H":	包装方式:
No.OF POS	G0=Gold Flash	101=10.16mm	R=载带包装
-10	SEE:TABLE 2	G1=1u" Gold	105=10.59mm
-15	No OF ROWS	G2=3u" Gold	126=12.60mm
...	-04	G3=5u" Gold	146=14.61mm
	-05	G4=10u" Gold	166=16.61mm
	...	G6=30u" Gold	

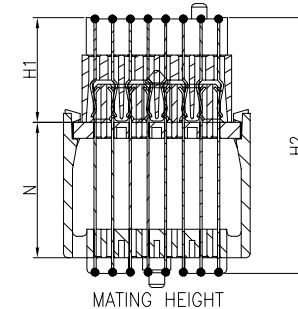
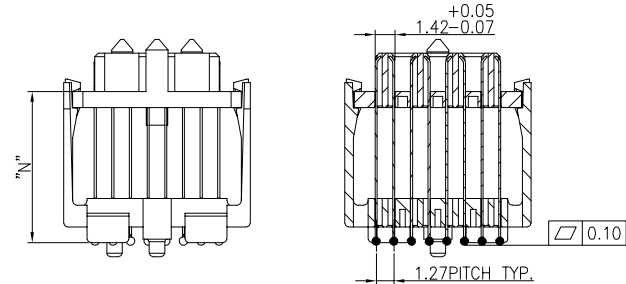
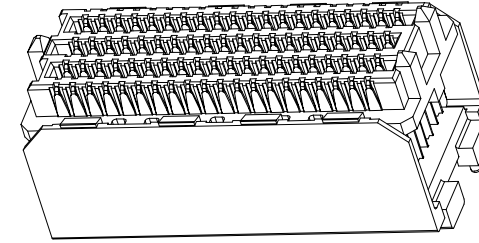
TABLE 1				
No.OF POS	"A"	"B"	"C"	"D"
-10	17.68	15.80	11.43	16.28
-15	24.03	22.15	11.78	22.63
-20	30.38	28.50	24.13	28.98
-30	43.08	41.20	36.83	41.68
-40	55.78	53.90	49.53	54.38
-50	68.48	66.60	62.23	67.08

TABLE 2		
No OF ROWS	"W"	"G"
-04	8.33	2.01
-05,-06	10.87	3.05
-08	13.41	3.05
-10	15.95	3.05

TABLE 3	
"N"	"H"
6.40	10.16
6.88	10.59
8.89	12.60
10.90	14.61
12.90	16.61



RECOMMENDED PCB LAYOUT(TOP SIDE)
PCB BOARD TOLERANCE±0.05



MATING HEIGHT

MATING HEIGHT	"N"	H1	H2
11.50mm	6.40	5.05	11.50
12.00mm	6.88		12.00
14.00mm	8.89		14.00
16.00mm	10.90		16.00
18.00mm	12.90	6.05	18.00
12.50mm	6.40		12.50
13.00mm	6.88		13.00
15.00mm	8.89		15.00
17.00mm	10.90		17.00
19.00mm	12.90	6.55	19.00
13.00mm	6.40		13.00
13.50mm	6.88		13.50
15.50mm	8.89		15.50
17.50mm	10.90	7.54	17.50
19.50mm	12.90		19.50
14.00mm	6.40		14.00
14.50mm	6.88		14.50
16.50mm	8.89		16.50
18.50mm	10.90		18.50
20.50mm	12.90		20.50

OPERATION

Mr.Zeng

2025.05.13

DESIGN

Jensen

2025.05.13

CHECK

Jack

2025.05.13

APPROVE

Andy

2025.05.13

DIM.

TOL

UNIT

mm

SCALE

1:1

PROJ.

Φ

DRAW NO.

SP-1736

REV

DATE

MODIFICATION DESCRIPTION

CHANGE

APPROVE

NEW

AO

REV

DATE

MODIFICATION DESCRIPTION

CHANGE

APPROVE

NEW

AO

REV

DATE

MODIFICATION DESCRIPTION

CHANGE

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